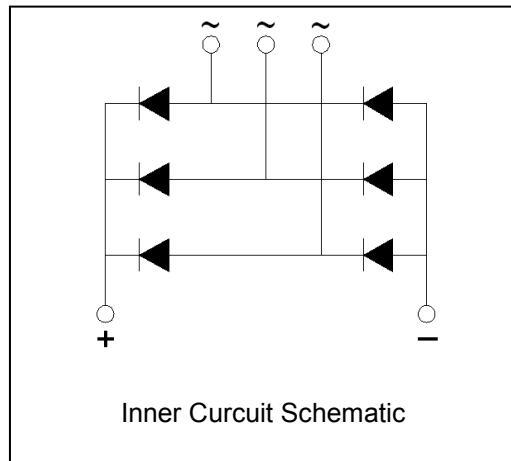


**THREE PHASE BRIDGE****Features**

- Low  $V_F$
- Direct Mounting to heatsink
- Low profile package
- Glass Passivation Chip
- Easy Connection
- Insulated Type



Inner Circuit Schematic

**Typical Applications**

- Inverters
- Welding
- UPS
- SMPS
- Battery Chargers
- DC Motors
- General Purpose DC Power Supplies

**Major Ratings and Characteristics**

Parameters	DPC300A 1K6V	Units
$I_o$	300	A
@ $T_c$	105	°C
$I_{FSM}$	480	A
@ 50Hz	620	A
$I^2t$	1370	$A^2s$
@ 60Hz	1230	$A^2s$
$V_{DRM}/V_{RRM}$	400 to 1600	V
$T_j$ range	- 40 to 150	°C

**ELECTRICAL SPECIFICATIONS****Voltage Ratings**

Type number	Voltage Code	$V_{RRM} / V_{DRM}$ , maximum repetitive peak reverse voltage V	$V_{RSM}$ , maximum non- repetitive peak rev. voltage V	$I_{RRM} / I_{DRM}$ max. @ $T_J = T_{J\max}$ mA
DPC300A .	04	400	500	5
	08	800	900	
	12	1200	1300	
	14	1400	1500	
	16	1600	1700	

**Forward Conduction**

Parameter	DPC300A	Units	Conditions					
$I_o$ Maximum DC output current @ Case temperature	300	A	120° Rect conduction angle					
	105	°C						
$I_{FSM}$ , Maximum peak, one-cycle forward, non-repetitive on state surge current	480	A	t = 10ms	No voltage reapplied	Initia $T_J = T_{J\max}$			
	620		t = 8.3ms					
	430		t = 10ms	100% $V_{RRM}$ reapplied				
	460		t = 8.3ms					
$I^2 t$ Maximum $I^2 t$ for fusing	1370	$A^2 s$	t = 10ms	No voltage reapplied				
	1230		t = 8.3ms					
	620		t = 10ms	100% $V_{RRM}$ reapplied				
	690		t = 8.3ms					
$I^2 \sqrt{t}$ Maximum $I^2 \sqrt{t}$ for fusing	15100	$A^2 \sqrt{s}$	t = 0.1 to 10ms, no voltage reapplied					
$V_{FM}$ Maximum forward voltage drop	1.25	V	$V_{FM} = 1.25$ V, $T_J = 25^\circ C$ , $t_p = 400 \mu s$ single junction					

**Insulation Table**

Parameter	DPC300A.	Units	Conditions	
$V_{INS}$ RMS insulation voltage	2500	V	$T = 25^\circ C$ all terminal shorted	$f = 50Hz$ , $t = 1s$

## Thermal and Mechanical Specifications

Parameter	DPC300A.	Units	Conditions
T <sub>J</sub> Maximum junction operating temperature range	- 40 to 150	°C	
T <sub>stg</sub> Maximum storage temperature range	- 40 to 150	°C	
R <sub>thJC</sub> Maximum thermal resistance, junction to case	0.1	K/W	DC operation per module
	1.0		DC operation per junction
	0.12		120° Rect conduction angle per module
	1. 0		120° Rect conduction angle per junction
R <sub>thJC</sub> Maximum I <sup>2</sup> √ t for fusing	0.10	K/W	Per module. Mounting surface smooth, flat and greased. Heatsink compound thermal conductivity = 0.42W/mK
T Mounting torque ± 10% to heatsink	3	Nm	A mounting compound is recommended and the torque should be rechecked after a period of 3 hours to allow for the spread of the compound.Lubricated threads.
wt Approximate weight	458	g	

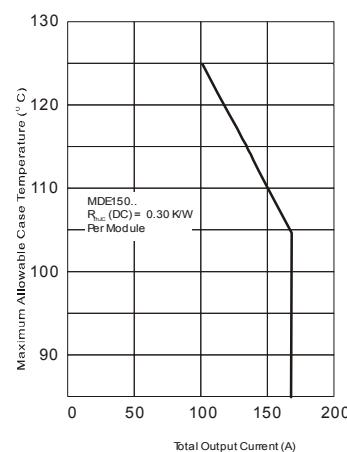
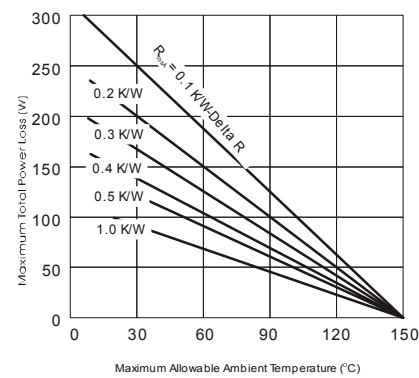
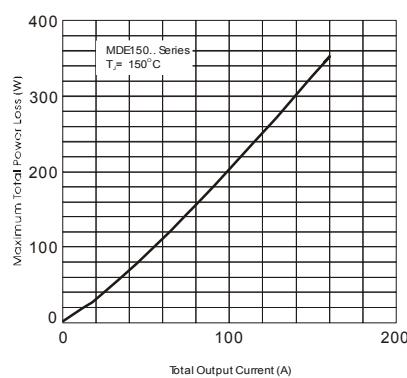


Fig. 1 - Current Rating Characteristics



**Outline Table**